NO. :



# **APPROVAL SHEET**

### MULTILAYER CERAMIC CAPACITOR

Automotive Grade (AEC-Q200 Qualified)

Approved by customer : (signing or stamping here)

SAMV	VHA CAPACITOR CO	D., LTD.
Prepared by	Checked by	Approved by
AL SE	for	74

## 2020. 02. 06.

## SAMWHA CAPACITOR CO., LTD.

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<	SPECIFIC		N SUMMARY >
SAMWHA Part no.		CQ1	L608C0G681J101NRB
Туре		MLCC fo	r Automotive Application
Items	Specification	Unit	Test Conditions
Capacitance	680	pF	_ Testing Frequency : 1 ±0.1 MHz
Capacitance Tolerance	± 5	%	Testing Voltage : 1 ±0.2 Vrms
Dissipation Factor	Max. 0.1	%	່ Should be measured at 25 ℃.
Insulation Resistance	Min. 100,000	MΩ	Should be measured with a DC voltage not exceeding rated voltage at 25 °C for 2 minutes of charging.
	1.60 ±0.15	L (mm)	- Capacitance Tolerance Code page 1/9
Chip Size	0.80 ±0.10	<b>W (</b> mm)	Chip size page 2/9
	0.80 ±0.10	<b>T (</b> mm)	Characteristics & Test Method page 3/9~6/9

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Enactment: Feb. 1	1, 2010	MULTILAYER CERAMIC CAPACITOR Automotive Grade							Pa	age	e 1/9			
	CU/ Power Please con hese Autor	tact sales	repres			roduc	t eng	ineers	befo	re us	ing			
1. General ( (1) Type D	<b>Code</b> Designation													
	<u>CQ</u>	<u>1608</u>	<u>C0G</u>	<u>681</u>	J	<u>101</u>	<u>N</u>	<u>R</u>	B					
	(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)					
2) Size	Th	is is expre le first two efficient Co	digits a				t two	digits	are wi	dth.				
						- turne - D	ande		Capa	oitonoc	Tolor	ance		
	Classification		Code		Temper	ature R	ange		Capa	ullance		Capacitance Tolerance ±30 ppm/℃		
	Classification Class		Code C0G		Temper -55 t	ature R o +125	-		Capa					
					-55 t		°C		Сара		pm/℃			
			C0G		-55 t -55 t	o +125	ິ ເ ເ		Capa	±30 p	pm/℃ 5%			
			C0G X7R		-55 t -55 t -55 t	o +125 o +125	ີ ເດີ ເດີ ເດີ			±30 p ±15 ±22	pm/℃ 5%			
	Class		COG X7R X7S X7T X6S		-55 t -55 t -55 t -55 t -55 t	o +125 o +125 o +125 o +125 o +125 o +105	ີ 3 3 3 3 3 3 3 3 3			±30 p ±15 ±22 •22% ~ ±22	pm/°C 5% 2% 33% 2%			
4) Capa	Class   Class    acitance Coc	de(Pico fara	C0G X7R X7S X7T X6S X5R ads) :		-55 t -55 t -55 t -55 t -55 t -55 t	o +125 o +125 o +125 o +125 o +125 o +105 to +85	・ 3 3 3 3 3 3 3 3 5 3 5 5 5 5 5 5 5 5 5 5 5 5 5		+	±30 p ±15 ±22 22% - ±22 ±15	pm/°C 5% 2% 33% 2%			
4) Capa The The ex) 1	Class   Class    Acitance Coo nominal Ca first two dig 104 = 10000 R denotes o 8R2 = 8.2 p acitance Tole Code	de(Pico fara pacitance of pits represe D0 pF decimal oF	COG X7R X7S X7T X6S X5R ads) : Value in ents signi	pF is ex ificant fig	-55 t -55 t -55 t -55 t -55 t -55 t	o +125 o +125 o +125 o +125 o +105 to +85 to +85 d by th nd the	C C C C C C C C C C C C C C C C C C C	-	+ mbers.	±30 p ±15 ±22 22% ~ ±22 ±15 the n Tole	pm/°C 5% 2% 2% 5% umber			
4) Capa The The ex) 1	Class   Class    Class    acitance Coo nominal Ca first two dig 104 = 10000 R denotes of 8R2 = 8.2 p acitance Tole Code B	de(Pico fara pacitance of pits represe D0 pF decimal oF	COG X7R X7S X7T X6S X5R ads) : Value in ents signi de Tolerance ± 0.1 pF	pF is ex ificant fig	-55 t -55 t -55 t -55 t -55 t -55 t	o +125 o +125 o +125 o +125 o +105 to +85 to +85 d by th nd the	C C C C C C C Iast o C C C C C C C C C C C C C C C C C C C	-	+ mbers.	±30 p ±15 ±22 -22% ~ ±22 ±15 the n Tole ± 2	pm/°C 5% 2% 2% 5% umber rance .0 %			
4) Capa The The ex) 1	Class   Class    Class    acitance Coc nominal Ca first two dig 104 = 10000 R denotes c 8R2 = 8.2 p acitance Tole Code B C	de(Pico fara pacitance of pits represe D0 pF decimal oF	COG X7R X7S X7T X6S X5R ads) : Value in ents signi de Tolerance $\pm 0.1 \text{ pF}$ $\pm 0.25 \text{ pF}$	pF is explicitly and the second secon	-55 t -55 t -55 t -55 t -55 t -55 t	o +125 o +125 o +125 o +125 o +105 to +85 to +85 d by th nd the	Code G C C C C C C C C C C C C C C C C C C	-	+ mbers.	$\pm 30 \text{ pl}$ $\pm 15$ $\pm 22$ -22%	pm/°C 5% 2% 2% 5% umber rance .0 %			
4) Capa The The ex) 1	Class   Class    Class    acitance Coo nominal Ca first two dig 104 = 10000 R denotes of 8R2 = 8.2 p acitance Tole Code B	de(Pico fara pacitance of pits represe D0 pF decimal oF	C0G X7R X7S X7T X6S X5R ads) : Value in ents signi de Tolerance ± 0.1 pF ± 0.25 pF ± 0.5 pF	pF is ex ificant fig	-55 t -55 t -55 t -55 t -55 t -55 t	o +125 o +125 o +125 o +125 o +105 to +85 to +85 d by th nd the	C C C C C C C Iast o C C C C C C C C C C C C C C C C C C C	-	+ mbers.	$\pm 30 \text{ pl}$ $\pm 15 $ $\pm 22 $ $\pm 22 $ $\pm 22 $ $\pm 15 $ the n Tole $\pm 2 $ $\pm 2 $ $\pm 1 $	pm/°C 5% 2% 2% 5% umber rance .0 %			
4) Capa The The ex) 1 5) Capa	Class   Class   Class    acitance Coc nominal Ca first two dig 104 = 10000 R denotes c 8R2 = 8.2 p acitance Tole Code B C D F	de(Pico fara pacitance of pits represe D0 pF decimal oF	COG X7R X7S X7T X6S X5R ads) : Value in ents signi de Tolerance $\pm 0.1 \text{ pF}$ $\pm 0.25 \text{ pF}$	pF is ex ificant fig	-55 t -55 t -55 t -55 t -55 t -55 t	o +125 o +125 o +125 o +125 o +105 to +85 to +85 d by th nd the	C C C C C C C C C C C C C C C C C C C	-	+ mbers.	$\pm 30 \text{ pl}$ $\pm 15 $ $\pm 22 $ $\pm 22 $ $\pm 22 $ $\pm 15 $ the n Tole $\pm 2 $ $\pm 2 $ $\pm 1 $	pm/°C 5% 2% 2% 5% umber rance .0 % 5 % 0 %			
4) Capa The The ex) 1 5) Capa	Class   Class    Class    acitance Coc nominal Ca first two dig 104 = 10000 R denotes c 8R2 = 8.2 p acitance Tole Code B C D F age Code	de(Pico fara pacitance ' pits represe D0 pF decimal oF erance Coo	COG X7R X7S X7T X6S X5R ads) : Value in ents signi de Tolerance $\pm 0.1 \text{ pF}$ $\pm 0.25 \text{ pF}$ $\pm 0.5 \text{ pF}$ $\pm 1.0 \%$	pF is ex ificant fig	-55 t -55 t -55 t -55 t -55 t -55 t ures a	o +125 o +125 o +125 o +125 o +105 to +85 d by the nd the	Code G J K M		+ mbers. enotes	$\pm 30 \text{ pl}$ $\pm 15 $ $\pm 22 $ $\pm 22 $ $\pm 22 $ $\pm 15 $ the n Tole $\pm 2 $ $\pm 1 $ $\pm 2 $ $\pm 1 $ $\pm 2 $ $\pm 1 $	pm/°C 5% 2% 2% 5% umber rance .0 % 5 % 0 % 0 %	of zero		
4) Capa The The ex) 1 5) Capa	Class   Class    Class    acitance Coc nominal Ca first two dig 104 = 10000 R denotes c 8R2 = 8.2 p acitance Tole Code B C D F age Code ode 6R3	de(Pico fara pacitance of pits represe D0 pF decimal oF	COG X7R X7S X7T X6S X5R ads) : Value in ents signi de Tolerance $\pm 0.1 \text{ pF}$ $\pm 0.25 \text{ pF}$ $\pm 0.25 \text{ pF}$ $\pm 1.0 \%$	pF is ex ificant fig	-55 t -55 t -55 t -55 t -55 t -55 t	o +125 o +125 o +125 o +125 o +105 to +85 to +85 d by th nd the	C C C C C C C C C C C C C C C C C C C	-	+ mbers.	$\pm 30 \text{ pl}$ $\pm 15 $ $\pm 22 $ $\pm 22 $ $\pm 22 $ $\pm 15 $ the n Tole $\pm 2 $ $\pm 2 $ $\pm 1 $	pm/°C 5% 2% 2% 5% umber rance .0 % 5 % 0 %			

- 8) Packing Code
  - R: 7" Reel Type, L: 13" Reel Type, B: Bulk Type

#### 9) Thickness option

Thickne	ess (mm)	Cada	Thickne	ss (mm)	Code	
t	Tolerance(±)	Code	t	Tolerance(±)	Code	
0.50	0.05	Blank	1.35	0.20	Н	
0.60	0.10	A	1.60	0.20	l	
0.80	0.10	В	1.80	0.20	J	
0.85	0.15	В	2.00	0.25	К	
1.00	0.15	E	2.50	0.25	L	
1.10	0.15	E	2.80	0.30	М	
1.15	0.15	E	3.20	0.30	Ν	
1.25	0.15	E	5.00	0.40	0	
1.30	0.20	E				

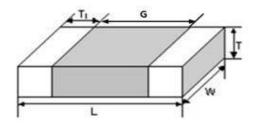
\*3216 Size  $\geq$ 2.2 $\mu$ F 100V  $\Rightarrow$  T : Tol±0.30

#### 2. Temperature Characteristics

See Page 6/9 (No.21)

#### 3. Constructions and Dimensions

(1) Dimensions



		Dimension								
Size Code	EIA Code	Length		Wi	dth	T4(min)	C(min)			
		L	Tol(±)	W	Tol(±)	T1(min.)	G(min.)			
1005	0402	1.00	0.05	0.50	0.05	0.05	0.30			
1608	0603	1.60	0.15	0.80	0.10	0.10	0.50			
2012	0805	2.00	0.20	1.25	0.15	0.10	0.65			
3216	1206	3.20	0.30	1.60	0.20	0.15	1.00			
3225	1210	3.20	0.40	2.50	0.25	0.15	1.05			
4520	1808	4.50	0.40	2.00	0.25	0.20	1.50			
4532	1812	4.50	0.40	3.20	0.30	0.20	1.50			
5750	2220	5.70	0.50	5.00	0.40	0.30	1.85			

\*3216 Size  $\geq$ 2.2 $\mu$ F 100V  $\Rightarrow$  L, W : Tol±0.30

#### (2) Construction of Termination



(Unit : mm)

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Spo	ecificatio	ns and	Test Methods (Fo	r Automotive Applica	ations)					
No	AEC-	Q200	Spec	cification	Test Methods and Conditions					
No.	Test	ltem	Class I	Class II	Test Methods and Conditions					
1	Pre-and Post- Electrical Test			-	-					
		Appearance	No defects which may affect	performance						
High 2 Temperature Exposure (Storage)		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0% (*Within ±12.5%)	Tomporatura : Max, operating tomporature (2%)					
		Q/D.F.	30pF min.: Q≧1000 30pF max.: Q≧400+20×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Temperature : Max. operating temperature±3 <sup>°</sup> C Maintenance Time : 1000+48/-0 hrs Let sit for 24±2 hours at room temperature, then measure.					
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ (Whichever is smaller)	£F (*25Ω-F)						
		Appearance	No defects which may affect	performance	Perform the 1000 cycles according to the four heat treatments					
		Capacitance Change	Within ±2.5% or ±0.25pF (Whichever is larger)	Within ±10.0% (*Within ±12.5%)	listed in the following table. Let sit for 24±2 hours at room temperature, then measure.					
			30pF min.:Q≧1000	Rated Voltage 16V min.: 0.05 max.	Step 1 2 3 4					
3	Temperature Cycle	Q/D.F.	30pF max.:Q≧400+20×C C: Nominal Capacitance (pF)	10V: 0.075 max. *0.2 max.	Min.     Max.       Temp.(°C)     operating temp.+0/-3     Room temp.+3/-0					
					Time(min)         15±3         1         15±3         1					
	I.R.		More than 10,000M $\Omega$ or 500 $\Omega$	Ω·F (*50Ω·F)	Initial measurement					
			(Whichever is smaller)		Perform the initial measurement according to Note 1 for Class II					
4	Destructive Physical Anal	ysis	No defects or abnormalities		Per EIA-469					
		Appearance	No defects which may affect	performance	Temperature : 25~65°C, Humidity : 80~98%					
		Capacitance Change	Within ±3.0% or±0.30pF (Whichever is larger)	Within ±12.5%	Cycle Time : 24 hrs/cycle, 10 cycles Let sit for 24±2 hours at room temperature, then measure.					
5	5 Moisture Resistance	Q/D.F.	30pF min.: Q≧350 10pF min. and 30pF max.: Q≧275+5/2xC 10pF max.: Q≧200+10xC C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	80-38%, 80-38%, 80-38%, 765 66 55 55 55 55 60 55 55 55 60 60 60 75 55 60 75 75 75 75 75 75 75 75 75 75					
		I.R.	More than 10,000MΩ or 500Ω (Whichever is smaller)	₽F (*50Ω·F)	15 10 5 0 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 Time (hrs)					
		Appearance	No defects which may affect	performance						
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	− Temperature : 85±3 ℃ Humidity : 80~85%					
6	Biased Humidity	Q/D.F.	30pF min.: Q≧200 30pF max.: Q≧100+10/3×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Applied Voltage : Rated Voltage and 1.3+0.2/-0V Maintenance Time : 1000+48/-0 hrs Let sit for 24±2 hours at room temperature, then measure.					
		I.R.	More than 1,000M $\Omega$ or 50 $\Omega$ ·F (Whichever is smaller)	(*5Ω·F)	The charge/discharge current is less than 50mA.					
		Appearance	No defects which may affect	performance	Temperature : Max operating Temp.±3 °C					
		Capacitance Change	Within ±3.0% or ±0.30pF (Whichever is larger)	Within ±12.5%	Applied Voltage : Rated Voltage × 100% Maintenance Time : 1000+48/-0 hrs					
7	Operational Life	Q/D.F.	30pF min.:Q $\geq$ 350 10pF min. and 30pF max.: Q $\geq$ 275+5/2×C 10pF max.: Q $\geq$ 200+10×C C: Nominal Capacitance (pF)	Rated Voltage 16V min.: 0.05 max. 10V: 0.075 max. *0.2 max.	Let sit for 24±2 hours at room temperature, then measure. The charge/discharge current is less than 50mA. Initial Measurement for Class II Applied 200% of the rated voltage for one hour at Max operating Temp.±3 °C					
		I.R.	More than 1,000M $\Omega$ or 50 $\Omega$ ·F (Whichever is smaller)	(*5Ω·F)	Remove and let sit for 24±2 hours at room temperature, then measure.					

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Spe	ecificatio	ons and	Test Methods (For	Automotive Applic	ation)				
	AEC-	-Q200	Speci	fication					
No.		Item	Class	Class II	Test Methods and Conditions				
8	External Visua	al	No defects or abnormalities		Visual inspection				
9	Physical Dime	ension	Within the specified dimensions		Using calipers				
		Appearance	No defects which may affect	performance	_				
		Capacitance Change	Within the specified tolerance						
10	Resistance		30pF min.: Q≧1000	Rated Voltage 50V: 0.025 max. 25V: 0.03 max.	Der Mill, CTD, 202 Method 245				
10	to Solvents	Q/D.F.	30pF max.: Q≧400+20×C	16V: 0.035 max.	Per MIL-STD-202 Method 215				
			C: Nominal Capacitance (pF)	10V: 0.05 max.					
			More than 10,000MΩ or 500Ω·l	*0.125 max. = (*500·F)	-				
		I.R.	(Whichever is smaller)	( )					
		Appearance	No defects which may affect	performance					
		Capacitance Change	Within the specified tolerance		Three shocks in each direction should be applied along 3 mutually perpendicular axes of the test specimen (18 shocks)				
	Mechanical		30pF min.:Q≧1000	Rated Voltage 50V: 0.025 max. 25V: 0.03 max.	Test Pulse				
11	Shock	Q/D.F.	30pF max.:Q≧400+20×C	16V: 0.035 max.	Wave form : Half-sine				
			C: Nominal Capacitance (pF)	10V: 0.05 max.	Duration : 0.5ms Peak value : 1,500G				
			Mara (har 40.000MO ar 5000)	*0.125 max.	Velocity change : 4.7m/s				
		I.R.	More than $10,000M\Omega$ or $500\Omega$ (Whichever is smaller)	- ("50 <u>0</u> ;F)					
		Appearance	No defects or abnormalities						
		Capacitance Change	Within the specified tolerance	_	The specimens should be subjected to a simple harmonic motion				
	Vibration			Rated Voltage 50V: 0.025 max.	having a total amplitude of 1.5mm. The entire frequency range of				
12		Vibration	Vibration	Vibration	Vibration	ion Q/D.F.	30pF min.:Q≧1000 30pF max.:Q≧400+20×C	25V: 0.03 max. 16V: 0.035 max.	10 to 2,000 Hz and return to 10 Hz should be traversed in 20
							C: Nominal Capacitance (pF)	10V: 0.05 max.	minutes. This cycle should be performed 12 times in each of three mutually perpendicular directions (total of 36 times).
				*0.125 max.	-				
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ ·l (Whichever is smaller)	- (*50Ω+F)					
		Appearance	No defects which may affect	performance					
		Capacitance Change	Within the specified tolerance		Temperature (Eutectic solder solution) : 260±5 ℃				
	Resistance		30pF min.:Q≧1000	Rated Voltage 50V: 0.025 max. 25V: 0.03 max.	Dipping Time : 10±1s				
13	to Soldering	Q/D.F.	30pF max.:Q≧400+20×C	16V: 0.035 max.	Let sit for 24±2 hours at room temperature, then measure.				
	Heat		C: Nominal Capacitance (pF)	10V: 0.05 max.	Initial measurement				
			M	*0.125 max.	Perform the initial measurement according to Note 1 for Class II.				
		I.R.	More than $10,000M\Omega$ or $500\Omega$ (Whichever is smaller)	- ("50 <u>0</u> ;F)					
		Appearance	No defects which may affect	performance	Perform the 300 cycles according to the two heat treatments listed				
		Capacitance	Within ±2.5% or ±0.25pF		in the following table.				
		Change	(Whichever is larger)	Within ±15%	Transfer Time : 20sec. max. Let sit for 24±2 hours at room temperature, then measure.				
	Thermal		20nE min :0 > 1000	Rated Voltage 50V: 0.025 max. 25V: 0.03 max.	Step 1 2				
14	Shock	Q/D.F.	30pF min.:Q≧1000 30pF max.:Q≧400+20×C	16V: 0.035 max.	Temp.(°C) Min. operating Max. operating				
			C: Nominal Capacitance (pF)	10V: 0.05 max.	temp.+0/-3 temp+3/-0				
			Mana (han 40.000) 40	*0.125 max.	Time(min.) 15±3 15±3				
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ (Whichever is smaller)	- (^50Ω·F)	Initial measurement				
					Perform the initial measurement according to Note 1 for Class II.				

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#### Specifications and Test Methods (For Automotive Application)

N -	AEC-0	Q200	Specif	fication		Teet Methode and Ora differen			
No.	Test		Class	Class	II	Test Methods and Conditions			
		Appearance Capacitance	No defects which may affect pe	erformance		-			
		Change	Within the specified tolerance	Rated Voltage 50V:	0.025 may	-			
15	ESD	Q/D.F.	30pF min.:Q≧1000 30pF max.:Q≧400+20xC C: Nominal Capacitance (pF)	25V: 16V:	0.023 max. 0.03 max. 0.035 max. 0.05 max.	Per AEC-Q200-002			
		I.R.	More than 10,000M $\Omega$ or 500 $\Omega$ ·F (Whichever is smaller)						
16	Solderability		95% of the terminations is to be s	oldered evenly and co	ontinuously.	<ul> <li>(a) Preheat at 155 °C for 4 hours, and then immerse the capacito in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5 °C.</li> <li>(b) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5 °C.</li> <li>(c) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution for 5+0/-0.5 seconds at 235±5 °C.</li> <li>(c) Steam aging for 8 hours, and then immerse the capacitor in a solution of ethanol and rosin. Immerse in eutectic solder solution of ethanol and rosin. Immerse in eutectic solder solution for 120±5 seconds at 260±5 °C.</li> </ul>			
		Appearance	No defects or abnormalities			The capacitance/Q/D.F. should be measured at 25 °C at the			
		Capacitance				frequency and voltage shown in the table.			
		Change	Within the specified tolerance			Class Capacitance (C) Frequency Voltage			
17	Electrical Characteriza- tion	Q/D.F.	30pF min.:Q≧1000 30pF max.:Q≧400+20xC C: Nominal Capacitance (pF) More than 100.000MΩ or 1.000Ω·F	16V:	0.03 max. 0.035 max. 0.05 max.	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$			
		I.R. at 25℃ I.R. at Max	(Whichever is smaller)	(*50Ω·F) (Whichever		Should be measured with a DC voltage not exceeding rated voltage at 25 °C and Max. operating temperature for 2 minutes of			
		operating Temp.	More than 10,000M $\Omega$ or 100 $\Omega$ -F (Whichever is smaller)	More than 1,000MΩ (*1Ω·F) (Whichever i		Applied 250% of the rated voltage for 1~5 seconds The charge/discharge current is less than 50mA.			
		Dielectric Strength	No dielectric breakdown or mecha	anical breakdown					
		Appearance	No defects which may affect pe	erformance		Apply a force in the direction shown in the following figure for 60±5 seconds.			
18	Board Flex	Capacitance Change	Within ±5.0% or ±0.5pF (Whichever is larger)	Within the specified	tolerance	45±2 45±2 45±2 Probe to exert bending force Speed: 1.0mm/s Printed circuit board under test Flexure for Class I: 3mm max. for Class II: 2mm max.			
		Appearance	No defects which may affect pe	l erformance					
	Terminal		Within ±5.0% or ±0.5pF			Apply 18N <sup>1)</sup> force in parallel with the test jig for 60±1 seconds. <sup>1)</sup> 10N for 1608(EIA:0603) size			

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Na	AEC	AEC-Q200 Spec		Speci	fication				uha da a				
No.	Test	Item	Class	1		Class II	Test Methods an			na Conditions			
			The chip endure follow	wing force.			,	Apply a force as shown in the following figure.					
			Chip Length	Thickn	ness (T)	Force	(i) Chip Lengtl Beam Spe				ength : 3.2r Speed : 2.5		
20			2.5mm max.	T≤0.	.5mm	8N	Beam Oper	30.0.311	11/5	Deam	speeu . 2.5	1111/5	
20	Beam Load To	est	2.01111 1107.	T>0.	.5mm	20N	Ļ						
i.			3.2mm min.	T<1.	25mm	15N	U U	Irc	on Board				
			5.211111 11111.	T≥	1.25	54.5N					0.6		
	<u> </u>	1											
I		Capacitance Change			X5R : Witl X7R : Witl X7S : With X6S : With X7T : With	hin ±15% hin ±22%	<ul> <li>(i) Class I</li> <li>The temperatumeasured in sequentially fr</li> <li>within the spe</li> <li>The capacitant</li> </ul>	step 3 as a om step 1 cified tole	a reference I through 5 rance for tl	e. When c , the capa ne temper	cycling the t acitance sh rature coef	temperatur hould be ficient.	
I	Capacitance	Temperature	0±30 ppm/℃				between the n 1, 3 and 5 by t					s in steps	
i.	Temperature	Coefficient	0-00 FF				Step	1	2	3	4	5	
21	Characteris- tics						Temp.(℃)	Room temp.±2	Min. operating temp.±3	Room temp.±2	Max. operating temp.±3	Room temp.±2	
I		Capacitance	ance Within ±0.2% or ±0.05pF				(ii) Class II The ranges of	•	•	•			
i		Drift	(Whichever is larger)				over the temp Max. operating		Ŭ	/lin. opera	ating tempe	rature to	
i.							Initial measure	ement					
							Perform the in	nitial mea	surement a	according	to Note 1 f	ior Class	

In the case of "\*" is specifications for "Thin Layer Large Capacitance Type"

Note 1. Initial Measurement for Class II

Perform a heat treatment at 150+0/-10 °C for one hour, and then let sit for 24±2 hours at room temperature, then measure.

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#### Packing

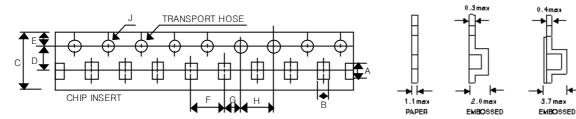
- (1) Bulk Packing
  - 1 1000 pcs per polybag
  - 2 5 polybags per inner box
  - 3 10 inner boxes per out box
- (2) Reel Packing
  - (1) 8~10 reels per inner box
  - 2 6 inner boxes per out box
- (3) Reel Dimensions

E	Π								(Ui	nit : mm)
	L I_	Mark	Size Code	EIA Code	Α	В	С	D	Е	w
\Q1/î	ſ <u>I</u>	7 " Reel	1005~3225	0402~1210	Ф <b>178±2</b>	Ф <b>50Min</b>	Ф13±0.5	Ф <b>21±0.8</b>	2±0.5	10±1.5
$\setminus$ $\square$			4520~4532	1808~1812	Ф180+0,-3	Ф60-0,+1	Φ13±0.2	Φ57-0+1	3±0.2	13±0.5
$\sim \rightarrow$	U w U 	13 " Reel	1005~3225	0402~1210	Ф <b>330±2</b>	Ф70Min	Ф13±0.5	Ф21±0.8	2±0.5	10±1.5

#### (4) Number of Package

Size Code	EIA Code	7"	13"		
		Quantity(pcs)/Reel	Quantity(pcs)/Reel		
1005	0402	10,000	50,000		
1608	0603	4,000	15,000		
2012	0805	3,000 ~ 4,000	8,000 ~ 15,000		
3216	1206	2,000 ~ 4,000	6,000 ~ 10,000		
3225	1210	1,000 ~ 3,000	4,000 ~ 10,000		
4520	1808	1,500 ~ 3,000	_		
4532	1812	500 ~ 1,000	1,500 ~ 5,000		

#### (5) Tape Dimensions



Size Code	EIA Code	А	В	С	D	E	F	G	н	J
1005	0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
1608	0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
2012	0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3216	1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
3225	1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4520	1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
4532	1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1

BLAN K	CHIPS	BLA	NK	LEADER
10 to 20pitch	•	20 to 4	0pitch	200 to 250mm
<b>•••••••••••••</b>	•••	+ ⊕⊕⊕⊕⊕	$\phi$	<del>¢</del>
			-0 0 0	]
DRA	WING DIRECTION			

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aution					
<ul> <li>Storage Condition</li> <li>When solderability is considered</li> <li>(1) Temperature: 25°C ± 10°C</li> <li>(2) Relative Humidity: Below 7</li> </ul>		ded to be used in 12 months.			
<ul> <li>The Regulation of Environment Never use materials mentioned Pb, Cd, Hg, Cr<sup>+6</sup>, PBB(Polybrock)</li> </ul>	d below in MLCC products	regulated this document. olybrominated diphenyl ethers), asbestos			
Mounting Position Choose a mounting position the imposed on the chip during flee board.		[Component direction] ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓ ↓			
		[Chip Mounting Close to Board Separation Point]			
<ol> <li>The sudden temperature changes damages to ceramic componer procedures should be required components.</li> <li>Please refer to the recommend shown in figures, and keep the within the range recommended Table 1</li> </ol>	hts. Therefore, the preheating for the soldering of ceramic ed soldering profiles as temperature difference( $\triangle$ T)	Recommended Reflow Soldering Profile for Lead Free Solder Infrared Reflow Temperature 250±10°C 200°C 160±10°C 140±10°C Preheating			
Size code (EIA Code)	Temperature Difference				
1005~3216 (0402~1206)	∆T≤190 ℃	60~120 sec. 30~60 sec.			
3225 (1210)	∆T≤130 ℃	Vapor Reflow Temperature			
		250±10°C 160±10°C 140±10°C Preheating 60~120 sec. 20 sec. max.			

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Note		
'Aging'/'De-aging' behavior of high dielectric constant type MLCCs		

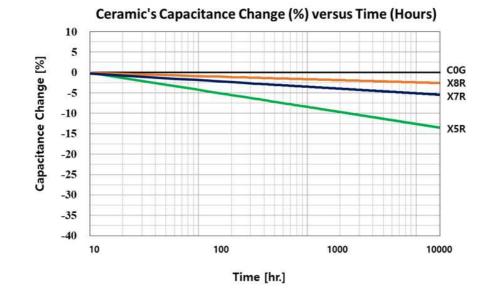
(Typically represented by X7R temperature characteristic of which main composition is BaTiO<sub>3</sub>)

'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric ceramic capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

#### $C_t = C_{24} (1 - k \log 10 t)$

where,

- $C_t\;$  : Capacitance value, t hours after the start of 'aging'
- $C_{\rm 24}$  : Capacitance value, 24 hours after its manufacture
- k : Aging constant (capacitance decrease per decade-hour)
- t : time, in hours, from the start of 'aging'



The capacitance value can be restored (also known as 'de-aged') by exposing the component to elevated temperatures approaching its curie temperature (approximately 120°C). This 'de-aging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing, or by baking at 150°C for about 1 hour.